ALIGNMENT MARK CONFIGURATION

CROSS-REFERENCE TO RELATED APPLICATION

This application is a continuation-in-part application of, and claims the priority benefit of, U.S. application serial no. 09/521,021, filed on March 8, 2000, ABN and entitled "Alignment Mark Configuration".

BACKGROUND OF THE INVENTION

Field of the Invention

The present invention relates to an integrated device. More particularly, the present invention relates to an alignment mark configuration.

Description of the Related Art

Photolithography is a critical step in the fabrication of an integrated device. For any general type of device fabrication, depending on the complexity of the product, the number of photolithography processes that are required to complete the product vary in number from about 10 to 18. In order to properly transfer a pattern on a mask to the wafer, the location of the alignment mark must be identified to accurately register the pattern on the mask with the previously formed pattern before performing the exposure process. The issue of discarding the entire wafer due to a mistake such as pattern misalignment in the pattern transferring process is thus prevented.

Proper identification of the alignment mark location mainly relies on the topography of the wafer surface. A scattering site or diffraction edge of an incident light is formed during the alignment process. The diffraction light reflected from the alignment mark is used as a signal, which is received by the overlay detector, to align